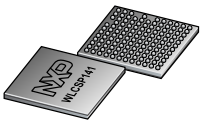

SOT2069-1

WLCSP141, wafer level chip scale package, 141 terminals, 0.35 mm pitch, 4.525 mm x 4.525 mm x 0.49 mm body (back side coating included)

3 September 2020 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP141
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	13-07-2020
Manufacturer package code	98ASA01653D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.495	4.525	4.555	mm
package width	4.495	4.525	4.555	mm
package height	-	0.49	0.525	mm
nominal pitch	-	0.35	-	mm
actual quantity of termination	-	141	-	

2 Package outline

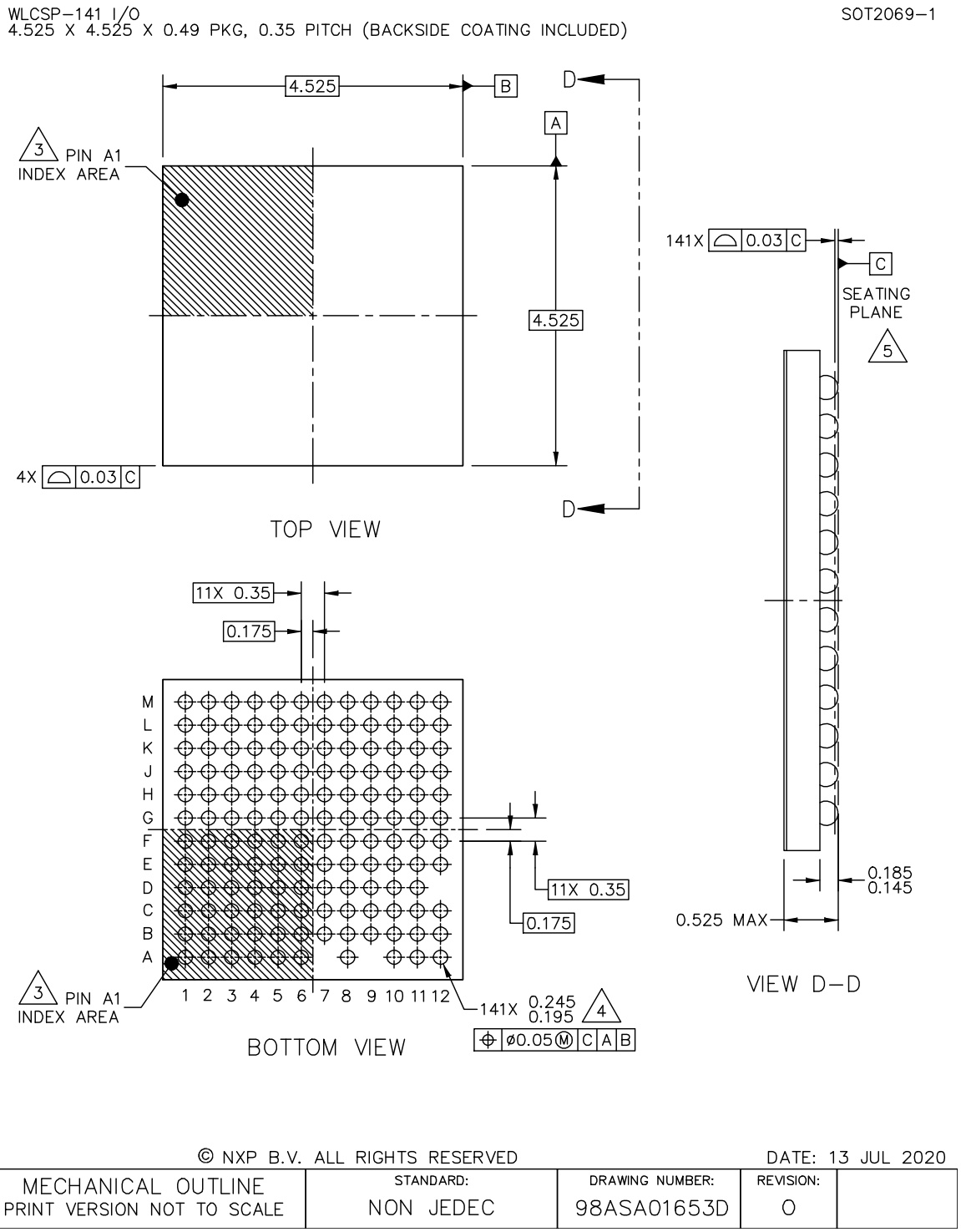

Figure 1. Package outline WLCSP141 (SOT2069-1)

All information provided in this document is subject to legal disclaimers.

© NXP B.V. 2020. All rights reserved.

3 Soldering

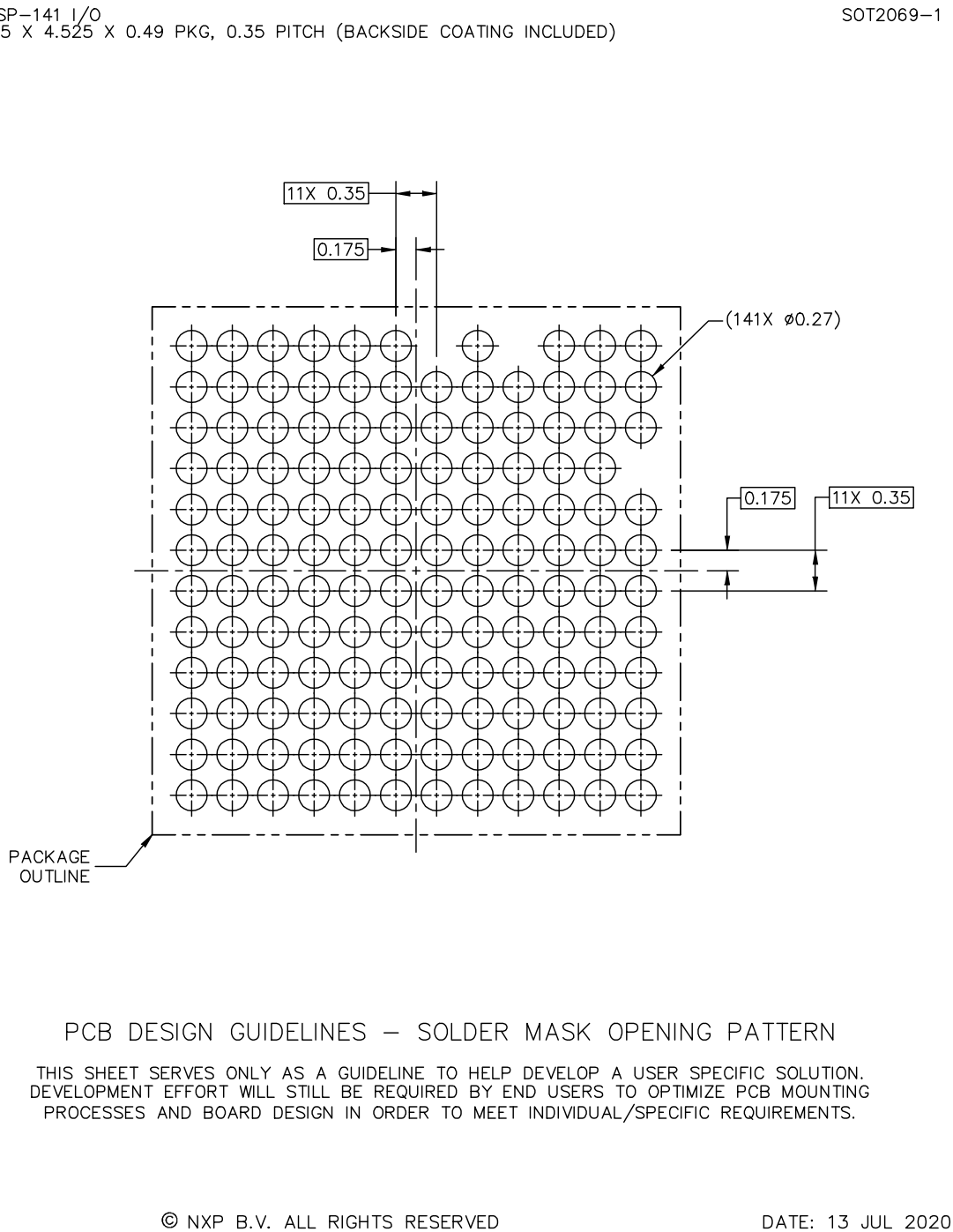

Figure 2. Reflow soldering footprint part1 for WLCSP141 (SOT2069-1)

All information provided in this document is subject to legal disclaimers.

© NXP B.V. 2020. All rights reserved.

WLCSP141, wafer level chip scale package, 141 terminals, 0.35 mm pitch, 4.525 mm x 4.525 mm x 0.49 mm body (back side coating included)

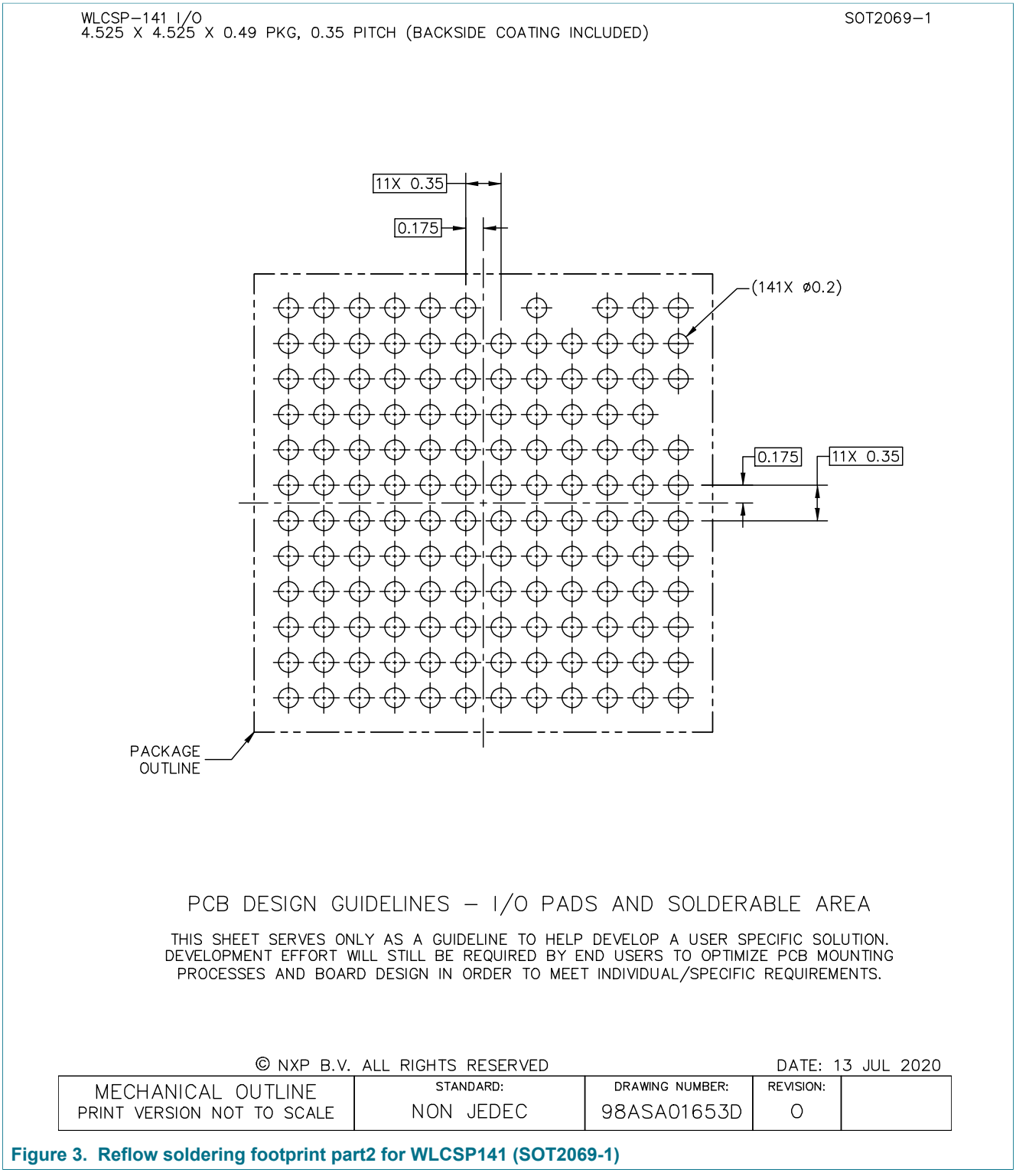

Figure 3. Reflow soldering footprint part2 for WLCSP141 (SOT2069-1)

All information provided in this document is subject to legal disclaimers.

© NXP B.V. 2020. All rights reserved.

WLCSP141, wafer level chip scale package, 141 terminals, 0.35 mm pitch, 4.525 mm x 4.525 mm x 0.49 mm body (back side coating included)

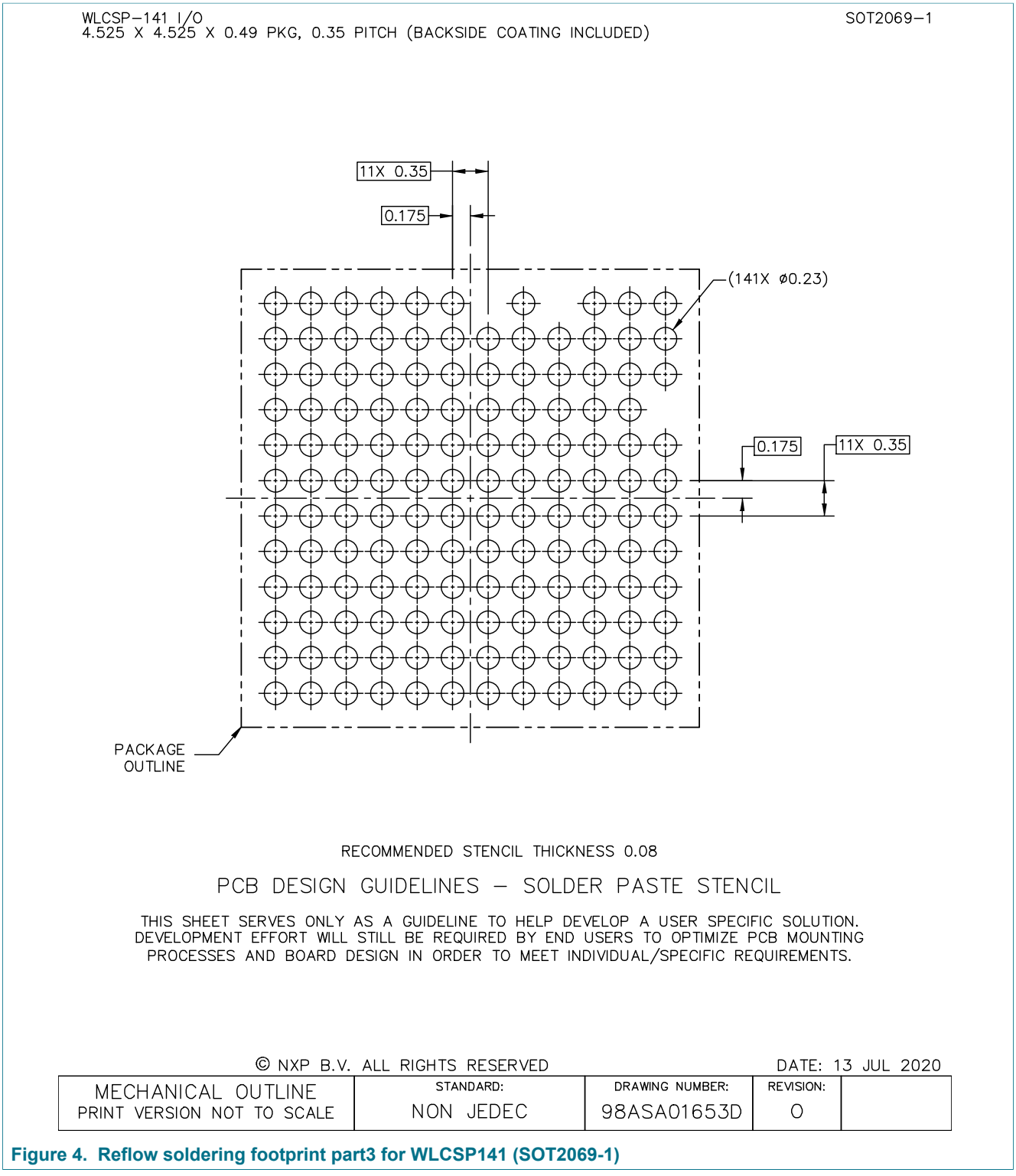

Figure 4. Reflow soldering footprint part3 for WLCSP141 (SOT2069-1)

All information provided in this document is subject to legal disclaimers.

© NXP B.V. 2020. All rights reserved.

WLCSP141, wafer level chip scale package, 141 terminals, 0.35 mm pitch, 4.525 mm x 4.525 mm x 0.49 mm body (back side coating included)

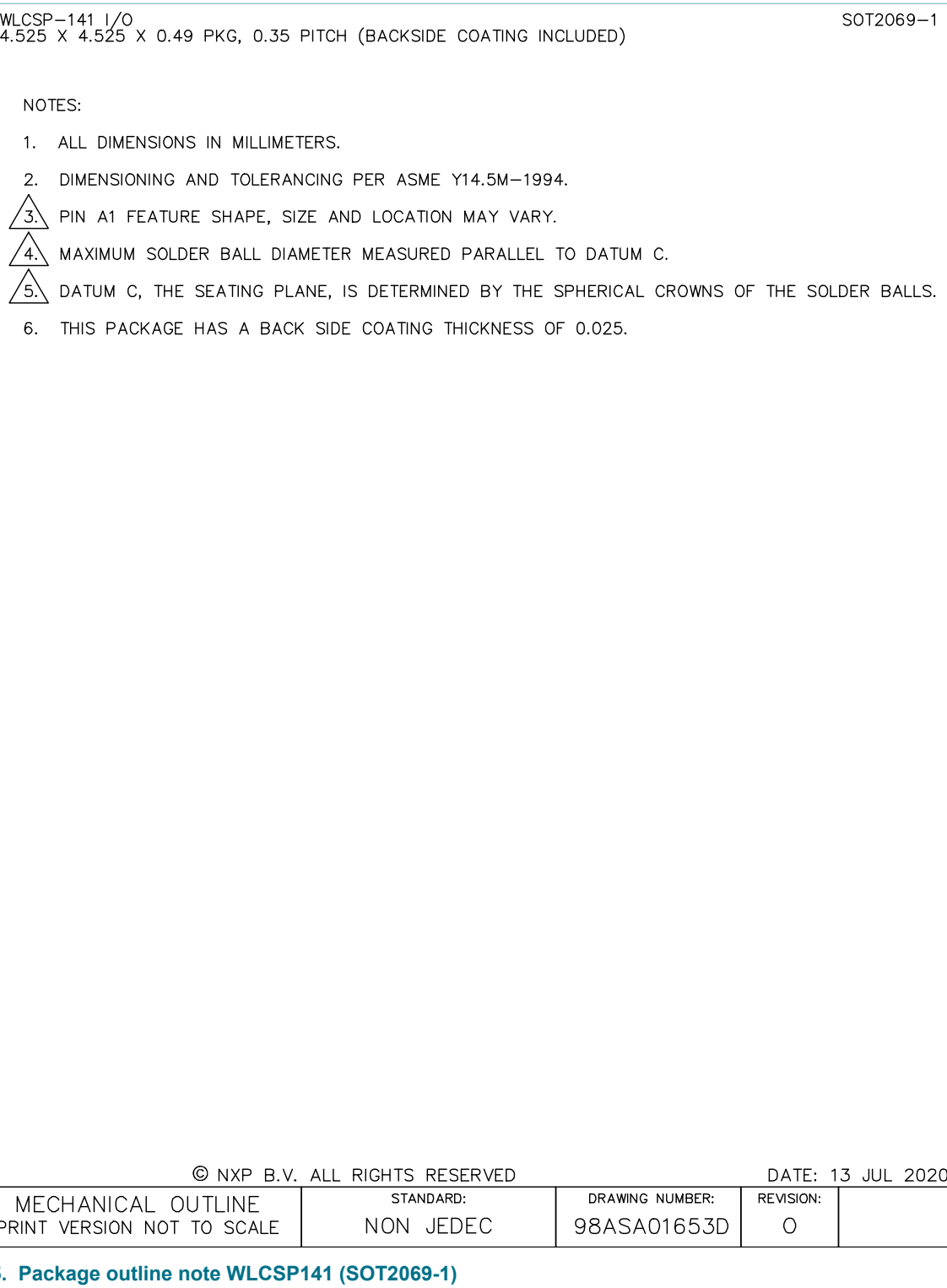

Figure 5. Package outline note WLCSP141 (SOT2069-1)

All information provided in this document is subject to legal disclaimers.

© NXP B.V. 2020. All rights reserved.

4 Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

All information provided in this document is subject to legal disclaimers.

© NXP B.V. 2020. All rights reserved.

SOT2069-1

WLCSP141, wafer level chip scale package, 141 terminals, 0.35 mm pitch, 4.525 mm x 4.525 mm x 0.49 mm body (back side coating included)

Contents

© NXP B.V. 2020. All rights reserved.

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 3 September 2020